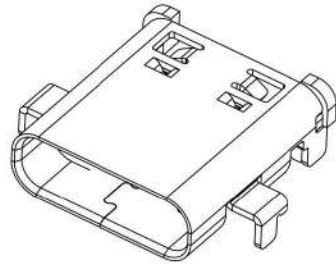
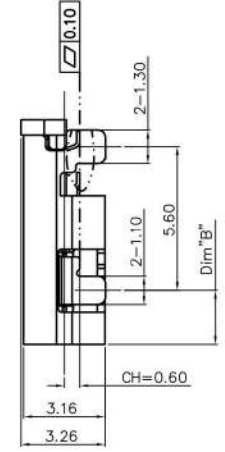
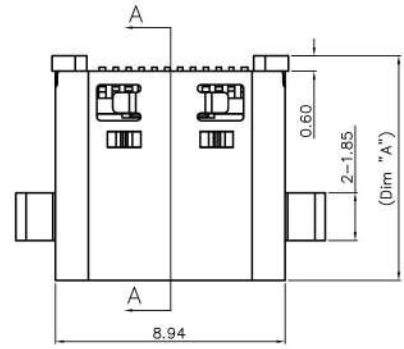


REV	ECN NO.	DISCRIPTION	CHEKED/DATE	APPD/DATE

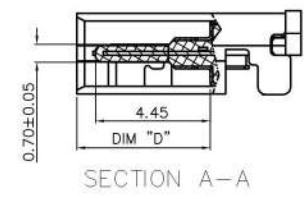
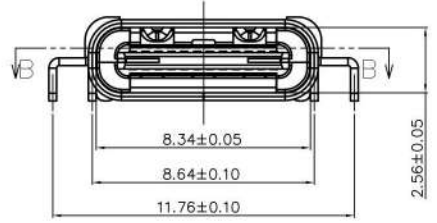
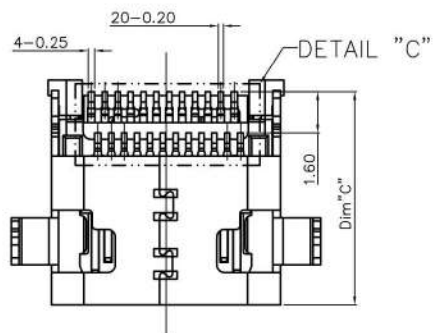


NOTES: 1.MATERIAL:  
MOLDING: LCP UL94 V-0  
CONTACT: COPPER ALLOY,  
GOLD PLATED Min ON CONTACT AREA,100u"  
Min TIN (LEAD FREE) ON SOLDER AREA,  
SHELL: SUS304-H,T=0.30±0.03mm  
30u" NICKEL PLATING OVER ALL.  
SHILD: SUS304-H,T=0.12±0.03mm

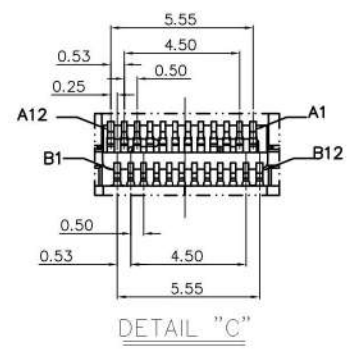
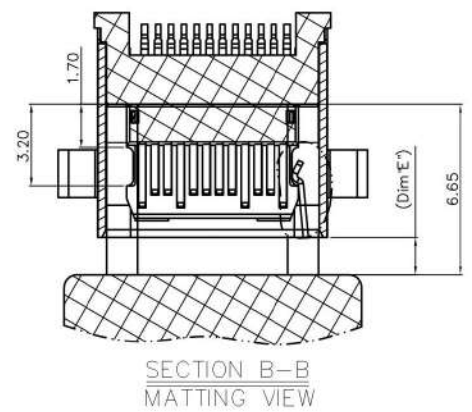
2.MECHANICAL:  
INSERTION: 5~20N.  
EXTRACTION: 8~20N AFTER TEST.  
DURABILITY: 10000 CYCLES

3.ELECTRICAL:  
CURRENT: 5A FOR VBUS;  
1.25A FOR GND PIN.  
0.25A FOR OTHER.  
VOLTAGE: 20 V MAX  
WITHSTANDING VOLTAGE: 100V AC R.M.S.  
CONTACT RESISTANCE: 40mΩ MAX.  
INSULATION RESISTANCE: 100MΩ MIN.

4.ENVIRONMENTAL  
TEMPERATURE RANGE -25°C ~ +85°C



**ITEM:USB3.1 TYPE-C 24PF-029**



8.35	1.75	7.90	4.80	1.8
Dim "A"	Dim "B"	Dim "C"	Dim "D"	Dim "E"

. X: ±0.25	X. : ±1°	APP.		DWG NO.	XWUC30037 (CU)
. XX: ±0.15	. X: ±0.5°	CHK.		TITLE	
. XXX: ±0.05	. XX: ±0.02°	DGN.		SERIES	
UNIT mm	SCALE 1:1	DRAW.			
REV. A0	SHEET: 1/2				